



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Min-Lung HUANG et al. Confirmation No: 8687  
Appl. No. : 10/820,855  
Filed : April 9, 2004  
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814  
Examiner : A. Kalam

Docket No.: : HUAN3262/REF  
Customer No: : 23364

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of August 27, 2007 and the Advisory Action of January 29, 2008, in connection with the above-identified application. The period for response to this Official Action has been extended to expire on February 27, 2008, by the filing herewith of a Petition for a Three-Month Extension of Time and payment of the required fee. Applicants submit that a Petition for a One-month extension of time with the required fee was submitted with the response filed on December 27, 2007.

A Request for Continuing Examination (RCE) is submitted and this amendment is the required submission.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.